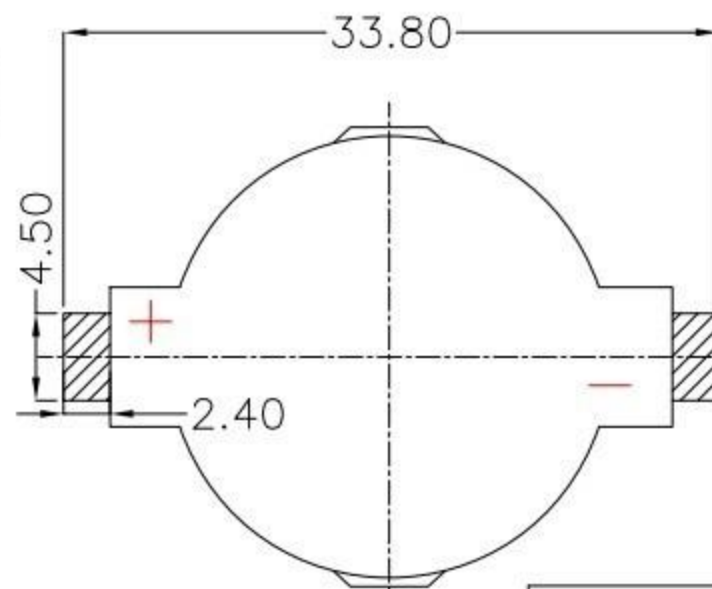
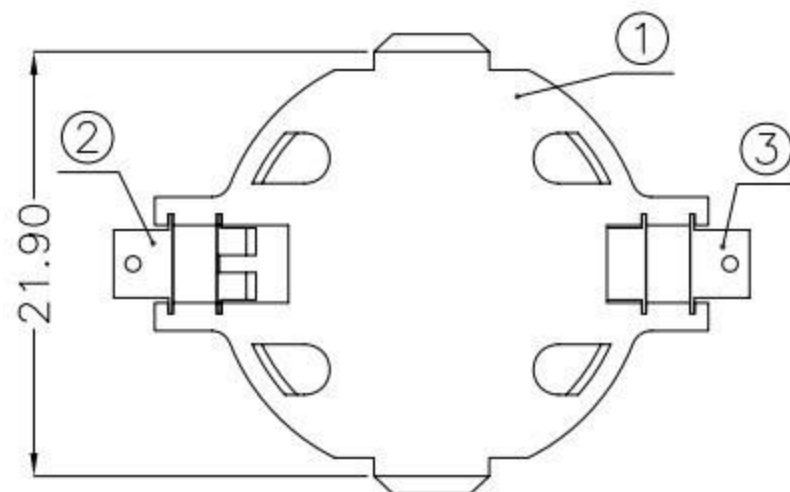
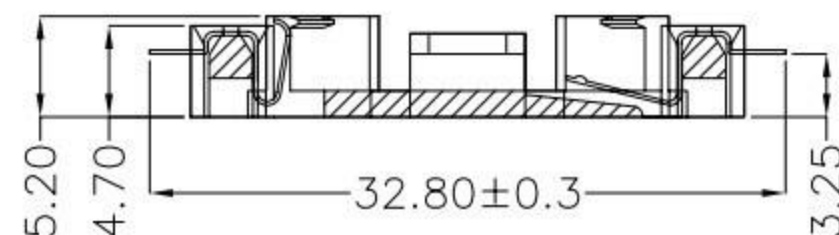
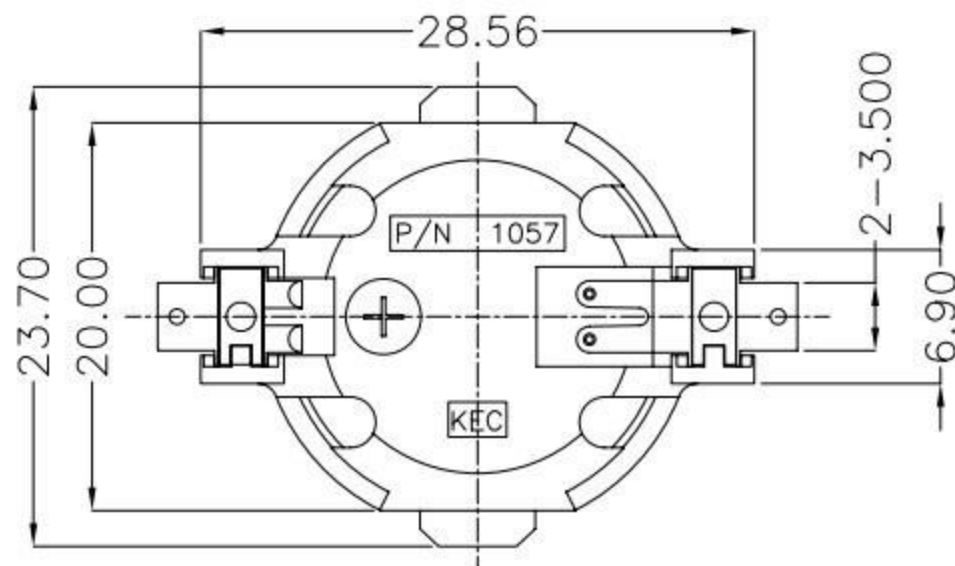




REV.	ECN NO.	REVISED	DATE



PCB Layout Diagram
Top View

NOTE:

1.MATERIAL:

a.HOUSING:LCP UL94V-0

b.CONTACT:PHOSPHOR BRONZE

(SURFACE PLATING:Sn=100u"-120u")

SEE ORDERING INFORMATION

2.ELECTRIC:

a.CONTACT RESISTANCE: 30 MILLIOHMS MAX

b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN

c.DIELECTRIC VOLTAGE: 500V AC ONE SEC LEVEL

d.OPERATING TEMPERATURE: -25°C~ +85°C

ORDERING INFORMATION

电池座系列

SMT 180° TYPE

PLATING:
A-Au1U"
J-Ni100U"~120U"
K-Sn100U"~120U"

MATERIAL:
1A-PBT BLACK
1B-PA66 BLACK
2A-PPA BROWN
2B-PPA BLACK
3A-PPS BROWN
3B-PPS BLACK
4A-LCP WHITE
4B-LCP BLACK

UNLESS OTHERWISE
SPECIFIED TOLERANCES

DECIMALS: ANGLES:
X :±0.30 X :±1°
X.X :±0.25 X.X :±0.5°
X.XX :±0.20
X.XXX :±0.10

WEIGHT: 1.45g

SHEET 1 OF 1



东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

DSND		DATE	2017-07-16
CHKD		DATE	2017-07-16
APVD		DATE	2017-07-16
SCALE: 2:1	SIZE: A4	VIEW: ④ ⑤	
UNIT: mm	REV.: A/0	OBJECT: MY	DRAW NO.:

TITLE:

PART NO.:

DRAW NO.:

NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR
3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.20mm	Gold Plating and Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.20mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	LCP	WHITE